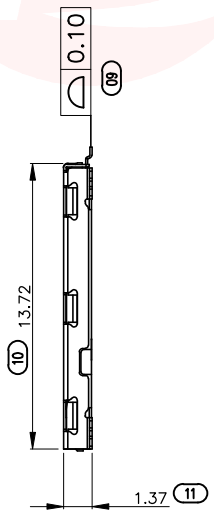
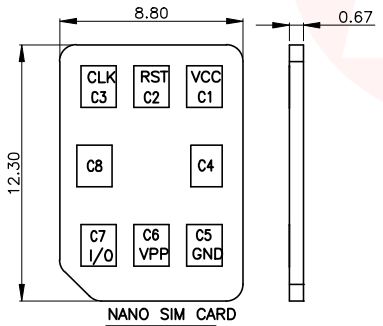
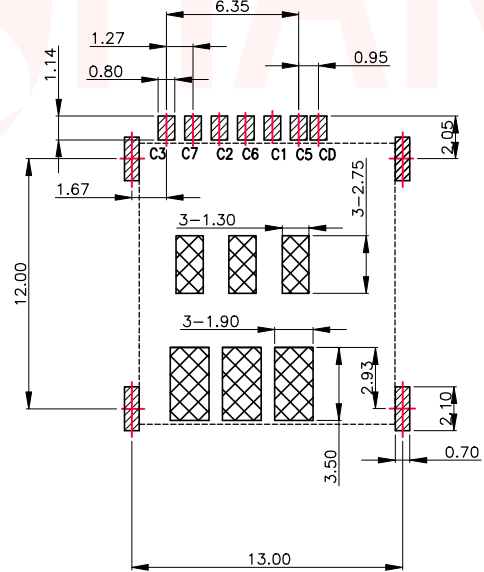
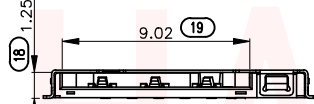
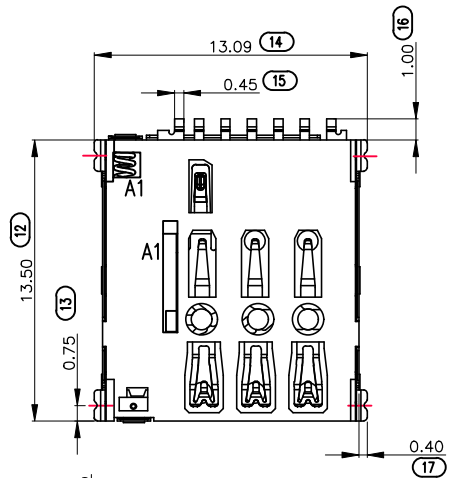
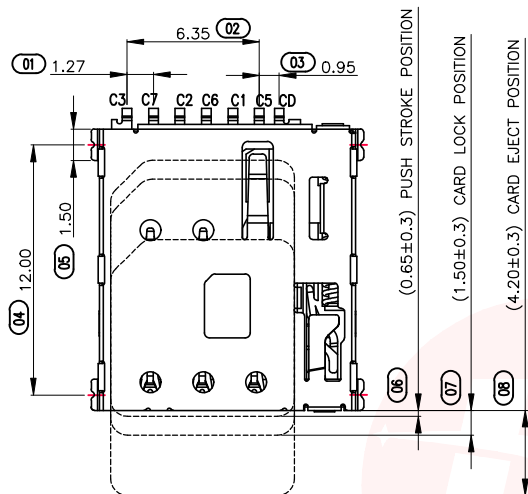


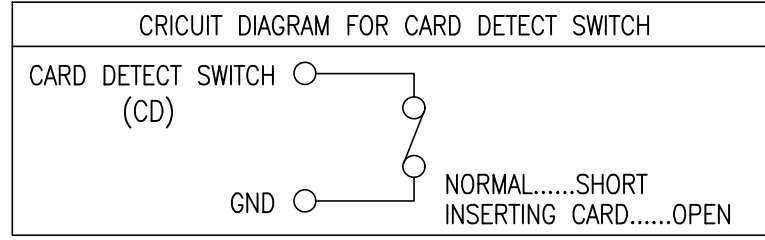


REV.	ECN NO OR DESCRIPTION	REVISED	DATE



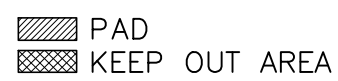
NOTES:

- 1) MATERIAL:
 - HOUSING: HI-TEMP. PLASIC UL 94V-0
 - CONTACT: COPPER ALLOY
 - SHELL: STAINLESS STEEL
- 2) PLATING :
 - TERMINAL:
 - CONTACT AREA: Au GOLD FLASH.
 - SOLDER AREA: AU GOLD FLASH.
 - UNDER PLATE: NICKEL.
 - SHELL: NICKEL PLATED OVER ALL.
 - SOLDER AREA: GOLD FLASH.
3. SPECIALITY:
 - 3.1 Rated current: 1.0A
 - 3.2 Rated voltage: 30V
 - 3.3 Contact Resistance: 50mΩ MAX
 - 3.4 Insulation Resistance: 1000MΩ MIN 500V DC
 - 3.5 Dielectric withstanding voltage: 500V AC.
 - 3.6 Solder ability: 260±0/-5℃, 30±10s.
 - 3.7 Durability: 5000 Cycles Min.
 - 3.8 Operating condition: Temperature -40℃ ~ +85℃; Humidity 80% R.H MAX



SIM pin Assignment	
PIN#	Name
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O

RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ±0.05



UNLESS OTHERWISE SPECIFIED TOLERANCES		东莞市汉博电子科技有限公司 DONGGUAN HANBO TECHNOLOGY CO., LTD	
DECIMALS:	ANGLES:	TITLE 6+1PIN 1.37H 无桩 PUSH PUSH Nano SIM CARD CONN.	
X ±0.30	X ±2°	DWN	xiong PART NO. SNO-1351SW-P7
X.X ±0.20	X.X ±1°	CHKD	lee SCALE:1:1 UNIT: mm
X.XX ±0.10		APVD	wang SIZE: A4 SHEET:10F 1 REV: A4
CUSTOMER COPY			